HALA 🗗

highly thermally conductive elastomer

TEL-X-SI is a low dielectric, high performance thermally conductive gap filler for an optimised thermal coupling between electronic packages and heat sinks even over large gaps or big tolerances. Through the specific formulation and filling with highly thermally and electrically conductive particles an extraordinary high anisotropic thermal conductivity is reached. Its conformal surface structure and high softness guarantee a very good compliance to the contact surfaces at low pressure. Thus the total thermal resistance is minimised.



## **PROPERTIES**

- ☐ High surface compliance and softness
- ☐ Thermal conductivity: 20 W/mK (anisotropic)
- Low dielectric
- Extraordinary chemical resistance and longterm stability
- Shock absorbing

## **AVAILABILITY**

□ Sheet 150 x 150 mm□ Double-side self tacky

(TEL-XXXXX-SI)

- Die cut parts
- Kiss cut parts on sheet
- Optional dielectric with PET film (TEL-XXXXX-SI-PET)

## **APPLICATION EXAMPLES**

Thermal link of:

- MOSFETs und IGBTs
- Power diodes or AC/DC converters
- Power modules

For use in Switch mode power supplies / Motor control units / Automotive engine management systems / UPS units / Solar systems

| Property                                     | Unit            | TEL-X0250-SI                                      | TEL-X0500-SI                                      |
|--|-----------------|---|---|
| Material                                     |                 | Silicone with highly thermally conductive fillers | Silicone with highly thermally conductive fillers |
| Colour                                       |                 | Dark Grey   | Dark Grey   |
| Thickness                                    | mm              | 0.25  | 0.50  |
| Hardness                                     | Shore 00        | 55  | 55  |
| UL Flammability                              | UL 94           | V0  | VO  |
| RoHS Conformity                              | 2011 / 65 / EU  | Yes   | Yes   |
| Thermal                                      |                 |   |   |
| Resistance <sup>1</sup> @ 90 PSI @ Thickness | °C-inch²/W (mm) | 0.05 (0.13)                                       | 0.09 (0.30)                                       |
| Resistance <sup>1</sup> @ 30 PSI @ Thickness | °C-inch²/W (mm) | 0.06 (0.20)                                       | 0.10 (0.41)                                       |
| Resistance¹ @ 10 PSI @ Thickness             | °C-inch²/W (mm) | 0.08 (0.23)                                       | 0.12 (0.47)                                       |
| Thermal Conductivity                         | W/mK            | 20  | 20  |
| Operating Temperature Range                  | °C              | - 50 to + 180                                     | - 50 to + 180                                     |
| Electrical                                   |                 |   |   |
| Dielectric Strength                          | kV/mm           | 0.9   | 0.9   |
| Volume Resistivity                           | Ohm - cm        | ≥ 1 x 10 <sup>12</sup>                            | ≥ 1 x 10 <sup>12</sup>                            |

Measurement technique according to: ¹ASTM D 5470. All data without warranty and subject to change. Please contact us for further data and information.

Thicknesses: 0.25 mm / 0.5 mm / 0.75 mm

mm vs. N/cm<sup>2</sup> (PSI) / Rth vs. N/cm<sup>2</sup> (PSI)

